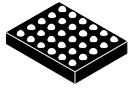


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

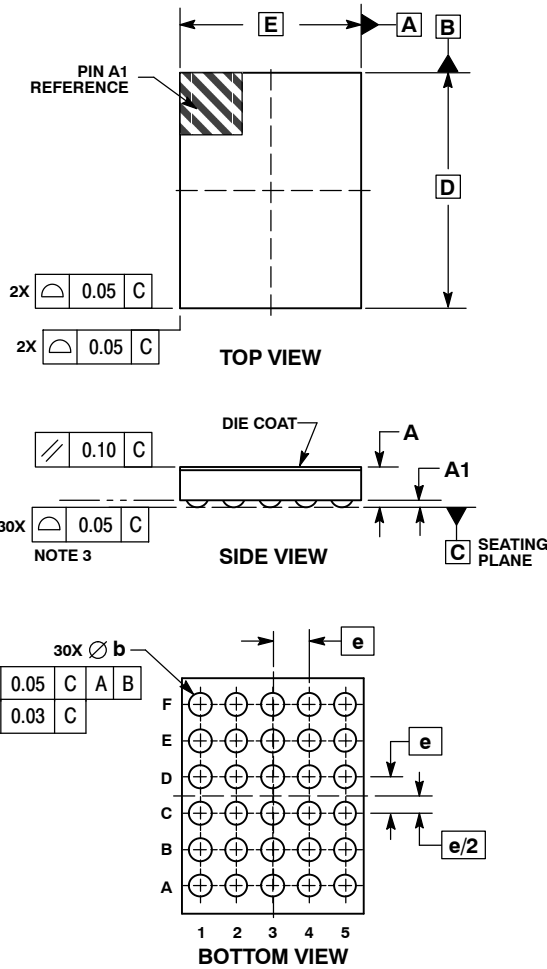
ON Semiconductor®



SCALE 4:1

**WLCSP30, 2.59x1.99**  
CASE 567HG  
ISSUE O

DATE 16 MAY 2013

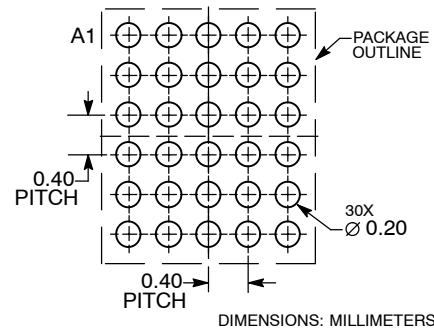


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.45
A1	0.03	0.13
b	0.15	0.25
D	2.59 BSC	
E	1.99 BSC	
e	0.40 BSC	

**RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>WLCSP30, 2.59X1.99</b>	<b>PAGE 1 OF 2</b>

